

Challenges of Nanotechnologies and Some Reliability Aspects

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Abstract

The paper take a fresh look at lessons learned from the last domain development. After a short introduction, is presented the advent of 3D Technology, the device shringing, carbon nanotubes, packaging and fabrication, critical dimensions, safety of environmental, health and safety (EHS), and the evaluation of reliability.

Keywords: nanotechnologies, reliability, Kaizen umbrella concept, Toyota way, lean production, innovation management

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